Typical Application

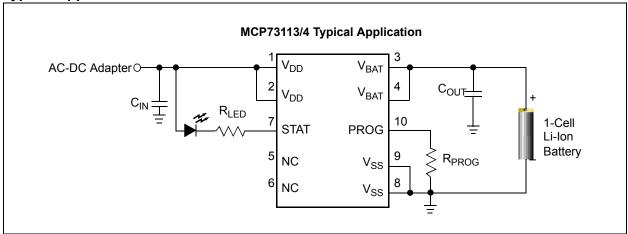


TABLE 1: AVAILABLE FACTORY PRESET OPTIONS

Charge Voltage	OVP	Pre- conditioning Charge Current	Pre- conditioning Threshold	Precondition Timer	Elapse Timer	End-of- Charge Control	Automatic Recharge	Output Status
4.10V	5.8V/6.5V	Disable/10%	66.5%/71.5%	Disable/ 32 Minimum	Disable/4 HR/ 6 HR/8 HR	5%/7.5%/ 10%/20%	No/Yes	Type 1/ Type 2
4.20V	5.8V/6.5V	Disable/10%	66.5%/71.5%	Disable/ 32 Minimum	Disable/4 HR/ 6 HR/8 HR	5%/7.5%/ 10%/20%	No/Yes	Type 1/ Type 2
4.35V	5.8V/6.5V	Disable/10%	66.5%/71.5%	Disable/ 32 Minimum	Disable/4 HR/ 6 HR/8 HR	5%/7.5%/ 10%/20%	No/Yes	Type 1/ Type 2
4.40V	5.8V/6.5V	Disable/10%	66.5%/71.5%	Disable/ 32 Minimum	Disable/4 HR/ 6 HR/8 HR	5%/7.5%/ 10%/20%	No/Yes	Type 1/ Type 2

- Note 1: I_{REG}: Regulated fast charge current.
 - 2: V_{REG}: Regulated charge voltage.
 - 3: I_{PREG}/I_{REG}: Preconditioning charge current; ratio of regulated fast charge current.
 - **4:** I_{TERM}/I_{REG}: End-of-Charge control; ratio of regulated fast charge current.
 - **5**: MCP73113: $V_{OVP} = 6.5V$, MCP73114: $V_{OVP} = 5.8V$.
 - **6:** V_{RTH}/V_{REG}: Recharge threshold; ratio of regulated battery voltage, 0% or 95%. 0% = Disabled.
 - 7: V_{PTH}/V_{REG}: Preconditioning threshold voltage.
 - 8: Output Status: Type 1 Fault Output Status = High-Z, Type 2 Fault Output Status = Flashing.

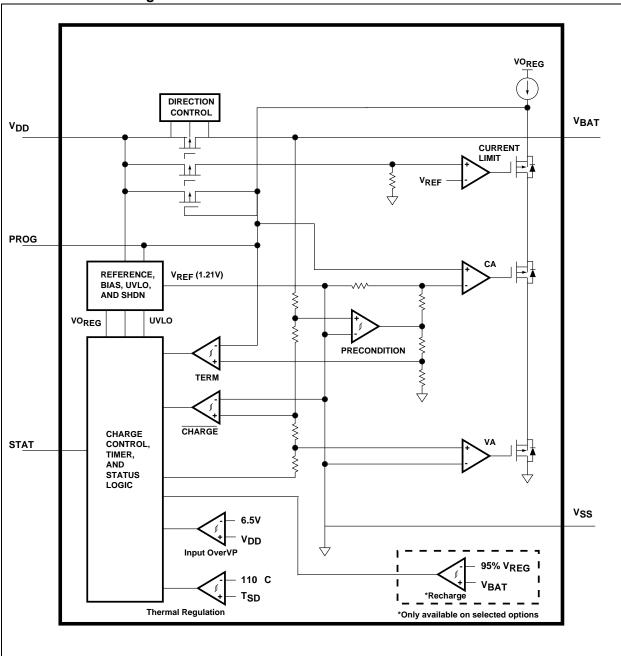
TABLE 2: STANDARD SAMPLE OPTIONS

Part Number	V _{REG}	OVP	I _{PREG} /I _{REG}	Pre-charge Timer	Elapse Timer	I _{TERM} /I _{REG}	Auto Recharge Threshold (0%=Disabled)	V _{PTH} /V _{REG}	Output Status
MCP73113-16S/MF	4.10V	6.5V	10%	32 Min.	6 HR	10%	95%	71.5%	Type 1
MCP73113-06S/MF	4.20V	6.5V	10%	32 Min.	6 HR	10%	95%	71.5%	Type 1
MCP73114-0NS/MF	4.20V	5.8V	10%	32 Min.	6 HR	10%	95%	71.5%	Type 1

Note 1: Customers should contact their distributor, representatives or field application engineer (FAE) for support and sample.

Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document. Technical support is available through the web site at: http://support.microchip.com.

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

† Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated, all limits apply for V_{DD} = [V_{REG} (Typical) + 0.3V] to 6V, $T_A = -40$ °C to +85°C. Typical values are at +25°C, $V_{DD} = [V_{REG} \text{ (Typical)} + 1.0V]$ **Parameters** Sym. Min. Units Conditions Max. Typ. Supply Input Input Voltage Range V_{DD} 4 16 V Operating Supply Voltage 4.2 6.5 ٧ V_{DD} Supply Current I_{SS} 4 5.5 μΑ Shutdown ($V_{DD} \le V_{BAT} - 150 \text{ mV}$) 700 1500 μΑ Charging 30 100 μΑ Standby (PROG Floating) Charge Complete; No Battery; 50 150 μΑ $V_{DD} < V_{STOP}$ **Battery Discharge Current** Output Reverse Leakage 0.5 2 μΑ Standby (PROG Floating) IDISCHARGE Current 2 Shutdown ($V_{DD} \leq V_{BAT}$, 0.5 μΑ or $V_{DD} < V_{STOP}$) 17 Charge Complete; V_{DD} is present 6 μΑ **Undervoltage Lockout UVLO Start Threshold** 4.25 ٧ V_{START} 4.10 4.15 **UVLO Stop Threshold** V_{STOP} 4.00 4.05 4.15 V **UVLO** Hysteresis V_{HYS} 100 mV Overvoltage Protection **OVP Start Threshold** ٧ MCP73113 V_{OVP} 64 6.5 66 V MCP73114 5.8 5.9 6.0 **OVP Hysteresis** 150 mV V_{OVPHYS} Voltage Regulation (Constant-Voltage Mode) Regulated Output Voltage ٧ $T_A = -5^{\circ}C$ to $55^{\circ}C$ 4.079 4.10 4.121 V_{REG} Options 4.179 4.20 4.221 ٧ $V_{DD} = [V_{REG}(Typical)+1V]$ 4.372 ٧ 4.328 4.35 $I_{OUT} = 50 \text{ mA}$ 4.378 4.422 ٧ 4.40 **Output Voltage Tolerance** 0.5 % **V_{RTOL}** -0.5 Line Regulation %/V $|(\Delta V_{BAT}/$ 0.05 0.20 $V_{DD} = [V_{REG}(Typical)+1V]$ to 6V $I_{OUT} = 50 \text{ mA}$ $V_{BAT})/\Delta V_{DD}$ % Load Regulation 0.05 0.20 I_{OUT} = 50 mA - 150 mA $|\Delta V_{BAT}/V_{BAT}|$ $V_{DD} = [V_{REG}(Typical)+1V]$ **PSRR** Supply Ripple Attenuation -46 dB I_{OLIT} = 20 mA, 10 Hz to 1 kHz

-30

dB

Note 1: Not production tested. Ensured by design.

 I_{OUT} = 20 mA, 10 Hz to 10 kHz

DC CHARACTERISTICS (CONTINUED)

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Battery Short Protection	<u> </u>		l .			
BSP Start Threshold	V _{SHORT}	_	1.7	_	V	
BSP Hysteresis	V _{BSPHYS}	_	150	_	mV	
BSP Regulation Current	I _{SHORT}	_	25	_	mA	
Current Regulation (Fast 0		nt-Current Mo	ode)			
Fast Charge Current	I _{REG}	130	· _	1100	mA	$T_A = -5^{\circ}C \text{ to } +55^{\circ}C$
Regulation	NEO .	_	130	_	mA	PROG = 10 kΩ
		_	1000	_	mA	PROG = 1.1 kΩ
Charge Current Tolerance	I _{RTOL}	_	10	_	%	
Preconditioning Current R		le Charge C	_	nt Mode)	,,,	
Precondition Current Ratio	I _{PREG} / I _{REG}	8	10	15	%	PROG = 1 k Ω to 10 k Ω
Trecondition current Natio	PREG / IREG	O	10	10	/0	$T_A = -5^{\circ}C \text{ to } +55^{\circ}C$
		_	100	_	%	No Preconditioning
Precondition Voltage	V _{PTH} / V _{REG}	64	66.5	69	%	V _{BAT} Low-to-High
Threshold Ratio	TIII KEG	69	71.5	74	%	BAI 0
Precondition Hysteresis	V _{PHYS}		100	_	mV	V _{BAT} High-to-Low (Note 1)
Charge Termination	19013				1	BAIg. to Let (cooks)
Charge Termination	I _{TERM} / I _{REG}	3.75	5	6.25	%	PROG = 1 kΩ to 10 kΩ
Current Ratio	TERM TREG	5.6	7.5	9.4	%	$T_A = -5^{\circ}C \text{ to } +55^{\circ}C$
		7.5	10	12.5	%	
		7.5 15	20	25	%	
Automotic Pochargo		10	20	25	70	
Automatic Recharge	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	02	05.0	07	0/	V High to Low
Recharge Voltage Threshold Ratio	V _{RTH} / V _{REG}	93	95.0	97	%	V _{BAT} High-to-Low No Automatic Recharge
Throughold Hadio		_	0	_	%	The final of teenings
Pass Transistor ON-Resist	tance		<u> </u>		70	<u> </u>
ON-Resistance	R _{DSON}		350		mΩ	V _{DD} = 4.5V, T _J = 105°C (Note 1
Status Indicator – STAT	NDSON		330		11152	VDD = 4.3 V, 1j = 103 0 (Note 1
Sink Current	Jan		20	35	mA	
	I _{SINK}		0.2		V	1 = 4 mA
Low Output Voltage	V _{OL}	_		0.5	_	I _{SINK} = 4 mA
Input Leakage Current	I _{LK}	_	0.001	l	μА	High-Impedance, V _{DD} on pin
PROG Input		4	1	04	1.0	T
Charge Impedance Range	R _{PROG}	1 70	-	21	kΩ	Insurandan on four Object description
Shutdown Impedance	R _{PROG}	70	200	-	kΩ	Impedance for Shutdown
PROG Voltage Range	V _{PROG}	0	_	5	V	
Automatic Power Down	1	.,,		1		loov, w
Automatic Power Down Entry Threshold	V _{PDENTRY}	V _{BAT} + 10 mV	V _{BAT} + 50 mV	_	V	$2.3V \le V_{BAT} \le V_{REG}$ V_{DD} Falling
Automatic Power Down Exit Threshold	V _{PDEXIT}	_	V _{BAT} + 150 mV	V _{BAT} + 250 mV	٧	2.3V ≤ V _{BAT} ≤ V _{REG} V _{DD} Rising
Thermal Shutdown					•	
Die Temperature	T _{SD}	_	150	_	°C	
Die Temperature Hysteresis	T _{SDHYS}	_	10	_	°C	

Note 1: Not production tested. Ensured by design.

AC CHARACTERISTICS

Electrical Specifications: Unless otherwise specified, all limits apply for V_{DD}= [V_{REG}(Typical)+0.3V] to 6V, T_A=-40°C to +85°C. Typical values are at +25°C, V_{DD} = [V_{REG} (Typical)+1.0V] **Parameters** Sym. Min. Тур. Max. Units Conditions **Elapsed Timer Elapsed Timer Period** 0 Hours Timer Disabled t_{ELAPSED} 3.6 4.0 4.4 Hours 6.0 6.6 5.4 Hours 7.2 8.0 8.8 Hours **Preconditioning Timer** Preconditioning Timer Period Disabled Timer 0 Hours t_{PRECHG} 0.4 0.5 0.6 Hours **Status Indicator** Status Output turn-off delay 500 I_{SINK} = 1 mA to 0 mA μs t_{OFF} (Note 1) I_{SINK} = 0 mA to 1 mA (Note 1) Status Output turn-on delay 500 μs t_{ON}

Note 1: Not production tested. Ensured by design.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Temperature Ranges						
Specified Temperature Range	T _A	-40	_	+85	°C	
Operating Temperature Range	T _J	-40	_	+125	°C	
Storage Temperature Range	T _A	-65	_	+150	°C	
Thermal Package Resistances						
Thermal Resistance, DFN-10 (3x3)	θ_{JA}	_	64	_	°C/W	4-Layer JC51-7 Standard Board Natural Convection
	θ_{JC}	_	12	_	°C/W	

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $V_{DD} = [V_{REG}(Typical) + 1V]$, $I_{OUT} = 50$ mA and $T_A = +25$ °C, Constant-Voltage mode.

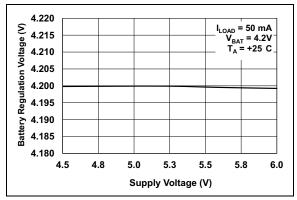


FIGURE 2-1: Battery Regulation Voltage (V_{BAT}) vs. Supply Voltage (V_{DD}) .

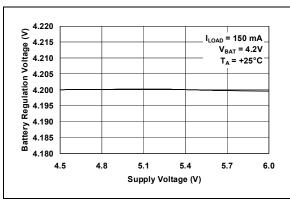


FIGURE 2-2: Battery Regulation Voltage (V_{BAT}) vs. Supply Voltage (V_{DD}) .

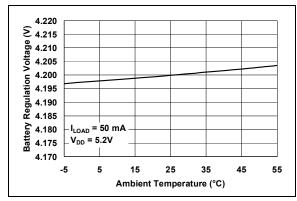


FIGURE 2-3: Battery Regulation Voltage (V_{BAT}) vs. Ambient Temperature (T_A) .

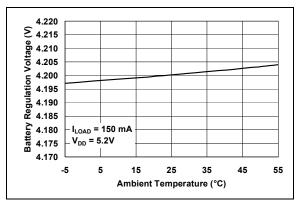


FIGURE 2-4: Battery Regulation Voltage (V_{BAT}) vs. Ambient Temperature (T_A) .

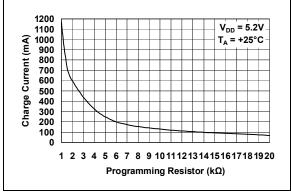


FIGURE 2-5: Charge Current (I_{OUT}) vs. Programming Resistor (R_{PROG}).

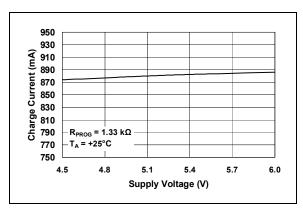


FIGURE 2-6: Charge Current (I_{OUT}) vs. Supply Voltage (V_{DD}).

TYPICAL PERFORMANCE CURVES (CONTINUED)

Note: Unless otherwise indicated, $V_{DD} = [V_{REG}(Typical) + 1V]$, $I_{OUT} = 10$ mA and $T_A = +25$ °C, Constant-Voltage mode.

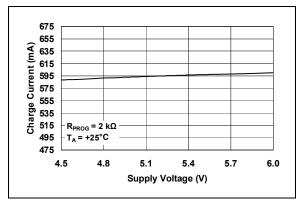


FIGURE 2-7: Charge Current (I_{OUT}) vs. Programming Resistor (R_{PROG}) .

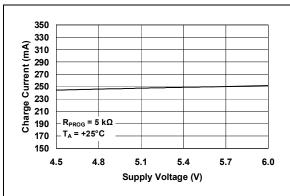


FIGURE 2-8: Charge Current (I_{OUT}) vs. Programming Resistor (R_{PROG}) .

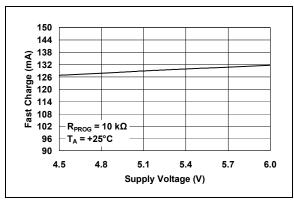


FIGURE 2-9: Charge Current (I_{OUT}) vs. Programming Resistor (R_{PROG}).

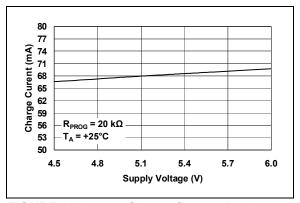


FIGURE 2-10: Charge Current (I_{OUT}) vs. Programming Resistor (R_{PROG}) .

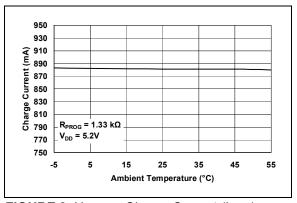


FIGURE 2-11: Charge Current (I_{OUT}) vs. Ambient Temperature (T_A) .

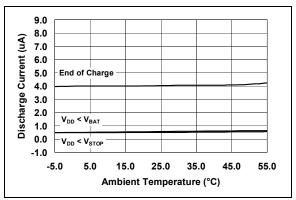


FIGURE 2-12: Output Leakage Current $(I_{DISCHARGE})$ vs. Ambient Temperature (T_A) .

TYPICAL PERFORMANCE CURVES (CONTINUED)

Note: Unless otherwise indicated, $V_{DD} = [V_{REG}(Typical) + 1V]$, $I_{OUT} = 10$ mA and $T_A = +25$ °C, Constant-Voltage mode.

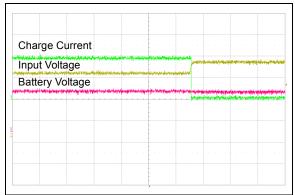


FIGURE 2-13: Overvoltage Protection Start (50 ms/Div).

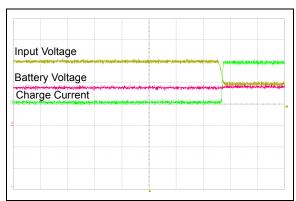


FIGURE 2-14: Overvoltage Protection Stop (50 ms/Div).

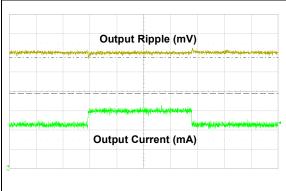


FIGURE 2-15: Load Transient Response $(I_{LOAD} = 50 \text{ mA}, \text{ Output: } 100 \text{ mV/Div},$ Time: $100 \mu \text{s/Div}).$

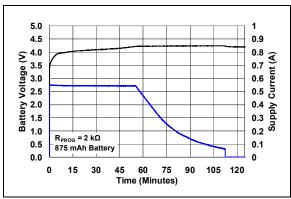


FIGURE 2-16: Complete Charge Cycle (875 mAh Li-lon Battery.

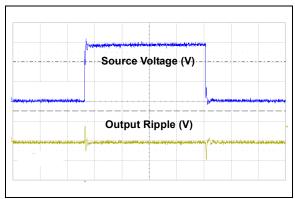


FIGURE 2-17: Line Transient Response $(I_{LOAD} = 10 \text{ mA}, \text{Output: } 1.0\text{V/Div}, \text{Source: } 2.0\text{V/Div}).$

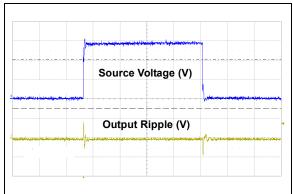


FIGURE 2-18: Line Transient Response $(I_{LOAD} = 100 \text{ mA}, \text{Output: } 1.0\text{V/Div}, \text{Source: } 2.0\text{V/Div}).$

3.0 PIN DESCRIPTION

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLES

MCP73113/4	Symbol III		Function				
DFN-10	Symbol	I/O	Function				
1, 2	V_{DD}	I	Battery Management Input Supply				
3, 4	V_{BAT}	I/O	Battery Charge Control Output				
5, 6	NC	_	No Connection				
7	STAT	0	Battery Charge Status Output				
8, 9	V_{SS}	_	Battery Management 0V Reference				
10	PROG	I/O	Battery Charge Current Regulation Program and Charge Control Enable				
11	EP		Exposed Pad				

3.1 Battery Management Input Supply (V_{DD})

A supply voltage of [V_{REG} (Typical) + 0.3V] to 6.0V is recommended. Bypass to V_{SS} with a minimum of 1 μ F. The V_{DD} pin is rated 18V absolute maximum to prevent sudden rise of input voltage from spikes or low-cost AC-DC wall adapter.

3.2 Battery Charge Control Output (V_{BAT})

Connect to the positive terminal of the battery. Bypass to V_{SS} with a minimum of 1 μF to ensure loop stability when the battery is disconnected.

3.3 No Connect (NC)

No connect.

3.4 Battery Management 0V Reference (V_{SS})

Connect to the negative terminal of the battery and input supply.

3.5 Status Output (STAT)

STAT is an open-drain logic output for connection to an LED for charge status indication in stand-alone applications. Alternatively, a pull-up resistor can be applied for interfacing to a host microcontroller. Refer to Table 5-2 for a summary of the status output during a charge cycle.

3.6 Current Regulation Set (PROG)

The fast charge current is set by placing a resistor from PROG to V_{SS} during Constant-Current (CC) mode. PROG pin is rated up to 5V with 6V absolute maximum value.

The PROG pin also serves as a charge control enable pin. Allowing the PROG pin to float or connecting the pin to an impedance greater than 200 k Ω will disable the MCP73113/4 charger. Refer to Section 5.5 "Constant Current MODE – Fast Charge" for details.

3.7 Exposed Pad (EP)

The Exposed Thermal Pad (EP) should be connected to the exposed copper area on the Printed Circuit Board (PCB) to enhance thermal power dissipation. Additional vias on the copper area under the MCP73113/4 device will improve the performance of heat dissipation and simplify the assembly process.

4.0 DEVICE OVERVIEW

The MCP73113/4 are simple, but fully integrated linear charge management controllers. Figure 4-1 depicts the operational flow algorithm.

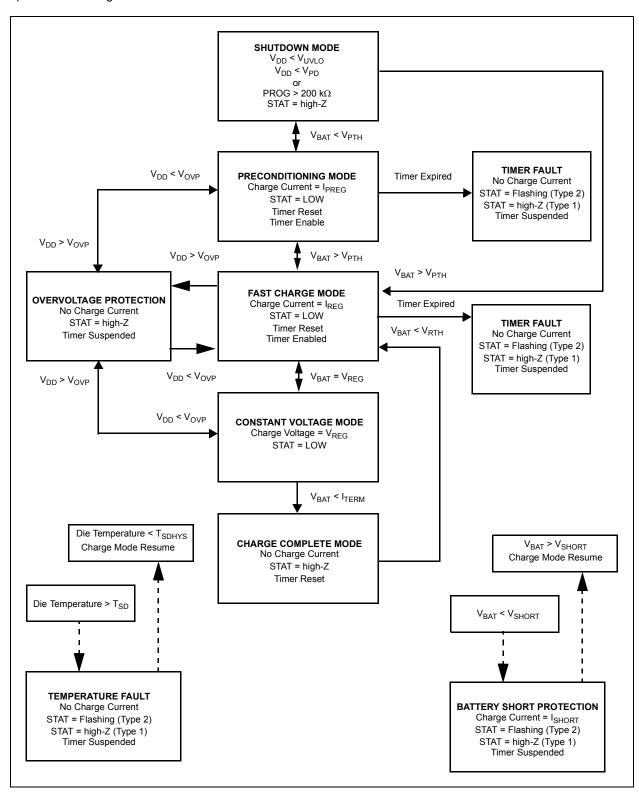


FIGURE 4-1: The MCP73113/4 Flowchart.

5.0 DETAILED DESCRIPTION

5.1 Undervoltage Lockout (UVLO)

An internal undervoltage lockout (UVLO) circuit monitors the input voltage and keeps the charger in Shutdown mode until the input supply rises above the UVLO threshold. In the event a battery is present when the input power is applied, the input supply must rise approximately 150 mV above the battery voltage before the MCP73113/4 device becomes operational.

The UVLO circuit places the device in Shutdown mode if the input supply falls to approximately 150 mV above the battery voltage. The UVLO circuit is always active. At any time, the input supply is below the UVLO threshold or approximately 150 mV of the voltage at the V_{BAT} pin, the MCP73113/4 device is placed in a Shutdown mode.

5.2 Overvoltage Protection (OVP)

An internal overvoltage protection (OVP) circuit monitors the input voltage and keeps the charger in Shutdown mode when the input supply rises above the OVP threshold. The hysteresis of OVP is approximately 150 mV for the MCP73113/4 device.

The MCP73113/4 device is operational between UVLO and OVP threshold. The OVP circuit is also recognized as overvoltage lockout (OVLO).

5.3 Charge Qualification

When the input power is applied, the input supply must rise 150 mV above the battery voltage before the MCP73113/4 becomes operational.

The automatic power-down circuit places the device in a Shutdown mode if the input supply falls to within +50 mV of the battery voltage.

The automatic circuit is always active. At any time the input supply is within +50 mV of the voltage at the V_{BAT} pin, the MCP73113/4 is placed in a Shutdown mode.

For a charge cycle to begin, the automatic powerdown conditions must be met and the charge enable input must be above the input high threshold.

5.3.1 BATTERY MANAGEMENT INPUT SUPPLY (V_{DD})

The V_{DD} input is the input supply to the MCP73113/4. The MCP73113/4 automatically enters a Power-Down mode if the voltage on the V_{DD} input falls to within +50 mV of the battery voltage. This feature prevents draining the battery pack when the V_{DD} supply is not present.

5.3.2 BATTERY CHARGE CONTROL OUTPUT (V_{BAT})

The battery charge control output is the drain terminal of an internal P-channel MOSFET. The MCP73113/4 devices provide constant current and voltage regulation to the battery pack by controlling this MOSFET in the linear region. The battery charge control output should be connected to the positive terminal of the battery pack.

5.3.3 BATTERY DETECTION

The MCP73113/4 detects the battery presence by monitoring the voltage at V_{BAT} . The charge flow will initiate when the voltage on V_{BAT} is below the $V_{RECHARGE}$ threshold. Refer to **Section 1.0 "Electrical Characteristics"** for $V_{RECHARGE}$ values. The value will be the same for the non-rechargeable device.

When $V_{BAT} > V_{REG}$ + Hysteresis, the charge will be suspended or not started, depending on the current charge status, to prevent overcharging.

5.4 Preconditioning

If the voltage at the V_{BAT} pin is less than the preconditioning threshold, the MCP73113/4 device enters a Preconditioning mode. The preconditioning threshold is factory set. Refer to **Section 1.0** "Electrical Characteristics" for preconditioning threshold options.

In this mode, the MCP73113/4 device supplies 10% of the fast charge current (established with the value of the resistor connected to the PROG pin) to the battery.

When the voltage at the V_{BAT} pin rises above the preconditioning threshold, the MCP73113/4 device enters the constant current (Fast Charge) mode.

Note: The MCP73113/4 also offer options with no preconditioning.

5.4.1 TIMER EXPIRED DURING PRECONDITIONING MODE

If the internal timer expires before the voltage threshold is reached for Fast Charge mode, a timer fault is indicated and the charge cycle terminates. The MCP73113/4 device remains in this condition until the battery is removed or input power is cycled. If the battery is removed, the MCP73113/4 device enters the Standby mode where it remains until a battery is reinserted.

Note: The typical preconditioning timer for MCP73113/4 is 32 minutes. The MCP73113/4 also offer options with no preconditioning timer.

5.5 Constant Current MODE – Fast Charge

During the Constant-Current mode, the programmed charge current is supplied to the battery or load.

The charge current is established using a single resistor from PROG to V_{SS} . The program resistor and the charge current are calculated using the following equations:

EQUATION 5-1:

 $I_{REG} = 1104 \times R^{-0.93}$ Where: $R_{PROG} = \text{kilo-ohms (k}\Omega)$ $I_{REG} = \text{milliampere (mA)}$

EQUATION 5-2:

$$R_{PROG} = 10^{\wedge} \frac{(log(I_{REG})/(-0.93))log}{I\overline{I}\,\overline{0}4}$$
 Where:
$$R_{PROG} = \text{kilo-ohms (k}\Omega)$$

$$I_{REG} = \text{milliampere (mA)}$$

Table 5-1 provides commonly seen E96 (1%) and E24 (5%) resistors for various charge current to reduce design time.

TABLE 5-1: RESISTOR LOOK-UP TABLE

Charge Current (mA)	Recommended E96 Resistor (Ω)	Recommended E24 Resistor (Ω)
130	10k	10k
150	8.45k	8.20k
200	6.20k	6.20k
250	4.99k	5.10k
300	4.02k	3.90k
350	3.40k	3.30k
400	3.00k	3.00k
450	2.61k	2.70k
500	2.32k	2.37k
550	2.10k	2.20k
600	1.91k	2.00k
650	1.78k	1.80k
700	1.62k	1.60k
750	1.50k	1.50k
800	1.40k	1.50k
850	1.33k	1.30k
900	1.24k	1.20k
950	1.18k	1.20k
1000	1.10k	1.10k
1100	1.00k	1.00k

Constant-Current mode is maintained until the voltage at the V_{BAT} pin reaches the regulation voltage, V_{REG} . When Constant-Current mode is invoked, the internal timer is reset.

5.5.1 TIMER EXPIRED DURING CONSTANT CURRENT – FAST CHARGE MODE

If the internal timer expires before the recharge voltage threshold is reached, a timer fault is indicated and the charge cycle terminates. The MCP73113/4 device remains in this condition until the battery is removed. If the battery is removed or input power is cycled, the MCP73113/4 device enters the Standby mode where it remains until a battery is reinserted.

5.6 Constant-Voltage Mode

When the voltage at the V_{BAT} pin reaches the regulation voltage, V_{REG} constant voltage regulation begins. The regulation voltage is factory set to 4.10V, 4.20V, 4.35V or 4.40V with a tolerance of $\pm 0.5\%$.

5.7 Charge Termination

The charge cycle is terminated when, during Constant-Voltage mode, the average charge current diminishes below a threshold established with the value of 5%, 7.5%, 10% or 20% of fast charge current or internal timer has expired. A 1 ms filter time on the termination comparator ensures that transient load conditions do not result in premature charge cycle termination. The timer period is factory set and can be disabled. Refer to Section 1.0 "Electrical Characteristics" for timer period options.

5.8 Automatic Recharge

The MCP73113/4 device continuously monitors the voltage at the V_{BAT} pin in the Charge Complete mode. If the voltage drops below the recharge threshold, another charge cycle begins and current is once again supplied to the battery or load. The recharge threshold is factory set. Refer to Section 1.0 "Electrical Characteristics" for recharge threshold options.

Note: The MCP73113/4 also offer options with no automatic recharge.

For the MCP73113/4 devices with no recharge option, the MCP73113/4 will go into Standby mode when termination condition is met. The charge will not restart until at least one of the following conditions have been met:

- Battery is removed from the system and inserted again
- V_{DD} is removed and plugged in again
- R_{PROG} is disconnected (or high-impedance) and reconnected

5.9 Thermal Regulation

The MCP73113/4 shall limit the charge current based on the die temperature. The thermal regulation optimizes the charge cycle time while maintaining device reliability. Figure 5-1 depicts the thermal regulation for the MCP73113/4 device. Refer to Section 1.0 "Electrical Characteristics" for thermal package resistances and Section 6.1.1.2 "Thermal Considerations" for calculating power dissipation.

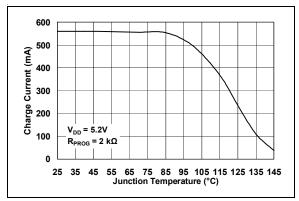


FIGURE 5-1: Charge Current (I_{OUT}) vs. Junction Temperature $(T_{,l})$.

5.10 Thermal Shutdown

The MCP73113/4 suspends charge if the die temperature exceeds +150°C. Charging will resume when the die temperature has cooled by approximately 10°C. The thermal shutdown is a secondary safety feature in the event that there is a failure within the thermal regulation circuitry.

5.11 Status Indicator

The charge status outputs are open-drain outputs with two different states: Low (L), and High-Impedance (high-Z). The charge status outputs can be used to illuminate LEDs. Optionally, the charge status outputs can be used as an interface to a host microcontroller. Table 5-2 summarizes the state of the status outputs during a charge cycle.

TABLE 5-2: STATUS OUTPUTS

CHARGE CYCLE STATE	STAT
Shutdown	high-Z
Standby	high-Z
Preconditioning	L
Constant Current Fast Charge	L
Constant Voltage	L
Charge Complete - Standby	high-Z
Temperature Fault	1.6 second 50% D.C. Flashing (Type2) high-Z (Type 1)
Timer Fault	1.6 second 50% D.C. Flashing (Type 2) high-Z (Type 1)
Preconditioning Timer Fault	1.6 second 50% D.C. Flashing (Type 2) high-Z (Type 1)

5.12 Battery Short Circuit Protection

When a single-cell Li-Ion battery is detected, an internal battery short circuit protection (BSP) circuit starts monitoring the battery voltage. When V_{BAT} is below the typical 1.7V battery short circuit protection threshold voltage, the charging behavior is postponed. A 25 mA (typical) detection current is supplied for recovering from the battery short circuit condition.

Preconditioning mode resumes when V_{BAT} raises above the battery short circuit protection threshold. The battery voltage must rise approximately 150 mV above the battery short circuit protection voltage before the MCP73113/4 device becomes operational.

6.0 APPLICATIONS

The MCP73113/4 devices are designed to operate with a host microcontroller or in stand-alone applications. The MCP73113/4 provides the preferred charge algorithm for Lithium-Ion and Lithium-Polymer cells Constant-current followed by Constant-voltage.

Figure 6-1 depicts a typical stand-alone application circuit, while Figure 6-2 depicts the accompanying charge profile.

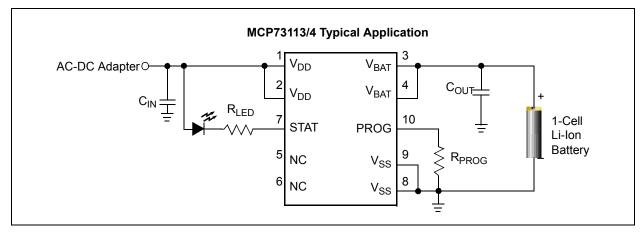


FIGURE 6-1: Typical Application Circuit.

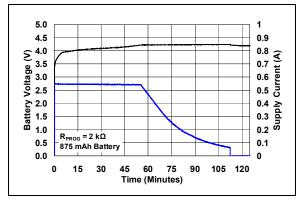


FIGURE 6-2: Typical Charge Profile (875 mAh Battery).

6.1 Application Circuit Design

Due to the low efficiency of linear charging, the most important factors are thermal design and cost, which are a direct function of the input voltage, output current and thermal impedance between the battery charger and the ambient cooling air. The worst-case situation is when the device has transitioned from the Preconditioning mode to the Constant-Current mode. In this situation, the battery charger has to dissipate the maximum power. A trade-off must be made between the charge current, cost and thermal requirements of the charger.

6.1.1 COMPONENT SELECTION

Selection of the external components in Figure 6-1 is crucial to the integrity and reliability of the charging system. The following discussion is intended as a guide for the component selection process.

6.1.1.1 Charge Current

The preferred fast charge current for Li-Ion/Li-Poly cells is below the 1C rate, with an absolute maximum current at the 2C rate. The recommended fast charge current should be obtained from the battery manufacturer. For example, a 500 mAh battery pack with 0.7C preferred fast charge current has a charge current of 350 mA. Charging at this rate provides the shortest charge cycle times without degradation to the battery pack performance or life.

Note: Please consult with your battery supplier or refer to the battery data sheet for preferred charge rate.

6.1.1.2 Thermal Considerations

The worst-case power dissipation in the battery charger occurs when the input voltage is at the maximum and the device has transitioned from the Preconditioning mode to the Constant-Current mode. In this case, the power dissipation is:

$$PowerDissipation = (V_{DDMAX} - V_{PTHMIN}) \times I_{REGMAX}$$

Where:

 V_{DDMAX} = the maximum input voltage

 I_{REGMAX} = the maximum fast charge current

 V_{PTHMIN} = the minimum transition threshold

voltage

Power dissipation with a 5V, ±10% input voltage source, 500 mA ±10% and preconditioning threshold voltage at 2.7V is:

EQUATION 6-1:

$$PowerDissipation = (5.5V - 2.7V) \times 550mA = 1.54W$$

This power dissipation with the battery charger in the DFN-10 package will result approximately 63°C above room temperature.

6.1.1.3 External Capacitors

The MCP73113/4 are stable with or without a battery load. In order to maintain good AC stability in the Constant-Voltage mode, a minimum capacitance of 1 μF is recommended to bypass the V_{BAT} pin to $V_{SS}.$ This capacitance provides compensation when there is no battery load. In addition, the battery and interconnections appear inductive at high frequencies. These elements are in the control feedback loop during Constant-Voltage mode. Therefore, the bypass capacitance may be necessary to compensate for the inductive nature of the battery pack.

A minimum of 1 μ F, is recommended for both the output capacitor and the input capacitor for typical applications.

TABLE 6-1: MLCC CAPACITOR EXAMPLE

MLCC Capacitors	Temperature Range	Tolerance
X7R	-55°C to +125°C	±15%
X5R -55°C to +85°C		±15%

Virtually any good quality output filter capacitor can be used, independent of the capacitor's minimum Effective Series Resistance (ESR) value. The actual value of the capacitor (and its associated ESR) depends on the output load current. A 1 μF ceramic, tantalum or aluminum electrolytic capacitor at the output is usually sufficient to ensure stability.

6.1.1.4 Reverse-Blocking Protection

The MCP73113/4 provide protection from a faulted or shorted input. Without the protection, a faulted or shorted input would discharge the battery pack through the body diode of the internal pass transistor.

6.2 PCB Layout Issues

For optimum voltage regulation, place the battery pack as close as possible to the device's V_{BAT} and V_{SS} pins, recommended to minimize voltage drops along the high current-carrying PCB traces.

If the PCB layout is used as a heat sink, adding many vias in the heat sink pad can help conduct more heat to the backplane of the PCB, thus reducing the maximum junction temperature. Figure 6-4 and Figure 6-5 depict a typical layout with PCB heat sinking.

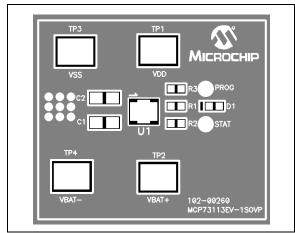


FIGURE 6-3: Typical Layout (Top).

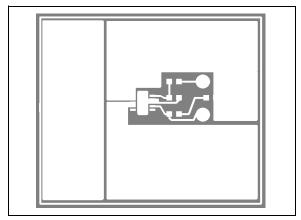


FIGURE 6-4: Typical Layout (Top Metal).

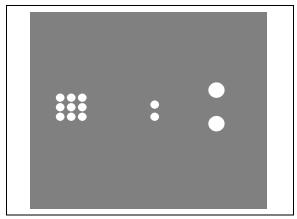


FIGURE 6-5: Typical Layout (Bottom).

7.0 PACKAGING INFORMATION

7.1 **Package Marking Information**

10-Lead DFN (3x3)

XXXX**YYWW** NNN

Standard *					
Part Number	Code				
MCP73113-06SI/MF	93HI				
MCP73113-16SI/MF	83HI				
MCP73114-0NSI/MF	9MHI				

Example:

93HI 1229 256

Legend: XX...X Customer-specific information

Υ Year code (last digit of calendar year) ΥY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code

(e3) Pb-free JEDEC designator for Matte Tin (Sn)

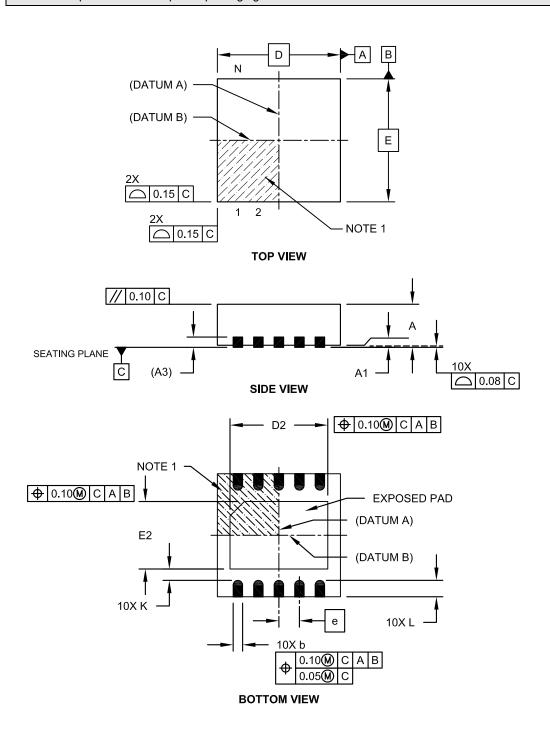
This package is Pb-free. The Pb-free JEDEC designator (@3)

can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

10-Lead Plastic Dual Flat, No Lead Package (MF) - 3x3x0.9mm Body [DFN]

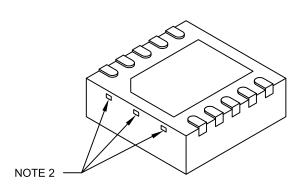
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing No. C04-063C Sheet 1 of 2

10-Lead Plastic Dual Flat, No Lead Package (MF) - 3x3x0.9mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	N	MILLIMETERS				
Dimension	Limits	MIN	NOM	MAX		
Number of Pins	N		10			
Pitch	е		0.50 BSC			
Overall Height	Α	0.80	0.90	1.00		
Standoff	A1	0.00	0.02	0.05		
Contact Thickness	A3	0.20 REF				
Overall Length	D		3.00 BSC			
Exposed Pad Length	D2	2.15	2.35	2.45		
Overall Width	E		3.00 BSC			
Exposed Pad Width	E2	1.40	1.50	1.75		
Contact Width	р	0.18	0.25	0.30		
Contact Length	Ĺ	0.30	0.40	0.50		
Contact-to-Exposed Pad	K	0.20	-	-		

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package may have one or more exposed tie bars at ends.
- 3. Package is saw singulated.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

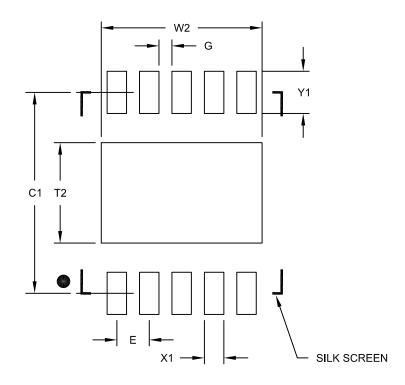
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-063C Sheet 2 of 2

10-Lead Plastic Dual Flat, No Lead Package (MF) - 3x3x0.9mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS			
Dimension	MIN	NOM	MAX	
Contact Pitch	Е		0.50 BSC	
Optional Center Pad Width	W2			2.48
Optional Center Pad Length	T2			1.55
Contact Pad Spacing	C1		3.10	
Contact Pad Width (X10)	X1			0.30
Contact Pad Length (X10)	Y1			0.65
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2063B

APPENDIX A: REVISION HISTORY

Revision D (February 2013)

The following is the list of modifications:

- 1. Updated the Functional Block Diagram.
- 2. Updated the DC Characteristics table.
- 3. Updated the Temperature Specifications table.
- 4. Updated Section 3.6 "Current Regulation Set (PROG)".
- 5. Updated Section 3.7 "Exposed Pad (EP)".
- 6. Updated Section 5.3.3 "Battery Detection".
- 7. Updated Equation 5-2.
- 8. Updated Section 5.12 "Battery Short Circuit Protection".
- Updated Section 6.1.1.3 "External Capacitors".

Revision C (January 2010)

The following is the list of modifications:

 DC Characteristics table: Removed the minimum and maximum values for the BSP Start Threshold parameter.

Revision B (July 2009)

The following is the list of modifications:

- Added MCP73114 device throughout the document.
- 2. Updated specifications for the MCP73113/4 device family throughout the document.
- 3. Updated package marking information.
- 4. Updated Product Identification System page.

Revision A (May 2009)

· Original Release of this Document.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	х хх	Exa	amples:
Device To	emperature Package	a)	MCP73113-06SI/MF: Single Cell Li-Ion/Li- Polymer Battery Device
	Range	b)	MCP73113-16SI/MF: Single Cell Li-lon/Li- Polymer Battery Device
Device:	MCP73113: Single Cell Li-lon/Li-Polymer Battery Device MCP73113T: Single Cell Li-lon/Li-Polymer Battery Device,	c)	MCP73113T-06SI-MF: Tape and Reel, Single Cell Li-Ion/Li- Polymer Battery Device
	Tape and Reel MCP73114: Single Cell Li-lon/Li-Polymer Battery Device MCP73114T: Single Cell Li-lon/Li-Polymer Battery Device, Tape and Reel	d)	MCP73113T-16SI/MF: Tape and Reel, Single Cell Li-Ion/Li- Polymer Battery Device
		a)	MCP73114-0NSI/MF: Single Cell Li-lon/Li- Polymer Battery Device
Temperature Range:	I = -40°C to +85°C (Industrial)	b)	MCP73114T-0NSI/MF: Tape and Reel, Single Cell Li-lon/Li- Polymer Battery Device
Package:	MF = Plastic Dual Flat No Lead, 3x3 mm Body (DFN), 10-Lead		

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